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L Number	Hits	Search Text	DB	Time stamp
1	564	360/244.1 360/244.3 360/245.8 360/245.9	USPAT; US-PGPUB	2004/08/21 15:57
2	60	@pd>20040417 and (360/244.1 360/244.3 360/245.8 360/245.9)	USPAT; US-PGPUB	2004/08/21 15:57
3	3	@ad<20000412 and (@pd>20040417 and (360/244.1 360/244.3 360/245.8 360/245.9))	USPAT; US-PGPUB	2004/08/21 16:31
4	4	@rlad<20000412 and (@pd>20040417 and (360/244.1 360/244.3 360/245.8 360/245.9))	USPAT; US-PGPUB	2004/08/21 15:58
5	7	(@ad<20000412 and (@pd>20040417 and (360/244.1 360/244.3 360/245.8 360/245.9))) (@rlad<20000412 and (@pd>20040417 and (360/244.1 360/244.3 360/245.8 360/245.9)))	USPAT; US-PGPUB	2004/08/21 16:26
6	197	ic with protect\$5 near7 (side or sidewall)	USPAT; US-PGPUB	2004/08/21 16:27
7	0	ic with protect\$5 near7 (side or sidewall) with micron	USPAT; US-PGPUB	2004/08/21 16:28
8	2	ic with layer near7 (side or sidewall) with micron	USPAT; US-PGPUB	2004/08/21 16:28
9	1	ic with protect\$5 near7 (side or sidewall) with "mu.m"	USPAT; US-PGPUB	2004/08/21 16:29
10	142	ic with (side or sidewall) with "mu.m"	USPAT; US-PGPUB	2004/08/21 16:29
11	379	(ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter")	USPAT; US-PGPUB	2004/08/21 16:35
12	198	@ad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter"))	USPAT; US-PGPUB	2004/08/21 16:36
13	117	@rlad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter"))	USPAT; US-PGPUB	2004/08/21 16:32
14	255	(@ad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter")) (@rlad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter"))	USPAT; US-PGPUB	2004/08/21 16:32
15	138	(ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") with (cover\$4 or layer\$4 or film or coat\$4)	USPAT; US-PGPUB	2004/08/21 16:40

16	61	@ad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") with (cover\$4 or layer\$4 or film or coat\$4))	USPAT; US-PGPUB	2004/08/21 16:48
17	38	@rlad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") with (cover\$4 or layer\$4 or film or coat\$4))	USPAT; US-PGPUB	2004/08/21 16:36
18	82	(@ad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") with (cover\$4 or layer\$4 or film or coat\$4))) (@rlad<20000412 and ((ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") with (cover\$4 or layer\$4 or film or coat\$4)))	USPAT; US-PGPUB	2004/08/21 16:36
19	18	(ic or "integrated circuit") with (side or sidewall) with ("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") with (cover\$4 or layer\$4 or film or coat\$4)	EPO; JPO; DERWENT; IBM_TDB	2004/08/21 16:44
20	313	(ic or "integrated circuit") with (side or sidewall) with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)	EPO; JPO; DERWENT; IBM_TDB	2004/08/21 16:46
21	5	("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter") and ((ic or "integrated circuit") with (side or sidewall) with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	EPO; JPO; DERWENT; IBM_TDB	2004/08/21 16:44
22	6	("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter" or angstrom) and ((ic or "integrated circuit") with (side or sidewall) with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	EPO; JPO; DERWENT; IBM_TDB	2004/08/21 16:45
23	398	(ic or "integrated circuit") with (side or sidewall) with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)	USPAT; US-PGPUB	2004/08/21 16:45
24	20	("mu.m" or micron or micrometer or "micro meter" or nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with (side or sidewall) with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	USPAT; US-PGPUB	2004/08/21 16:47

25	5245	(ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)	USPAT; US-PGPUB	2004/08/21 16:50
26	165	(nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	USPAT; US-PGPUB	2004/08/21 16:50
27	288	("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	USPAT; US-PGPUB	2004/08/21 16:48
28	87	@ad<20000412 and ((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))	USPAT; US-PGPUB	2004/08/21 16:49
29	53	@rlad<20000412 and ((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))	USPAT; US-PGPUB	2004/08/21 16:48
30	108	(@ad<20000412 and ((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))) (@rlad<20000412 and ((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))))	USPAT; US-PGPUB	2004/08/21 16:48
31	85	("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	USPAT; US-PGPUB	2004/08/21 16:51
32	49	@ad<20000412 and (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))	USPAT; US-PGPUB	2004/08/21 16:51
33	30	@rlad<20000412 and (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))	USPAT; US-PGPUB	2004/08/21 16:49

34	60	(@ad<20000412 and (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))) (@rlad<20000412 and (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))))	USPAT; US-PGPUB	2004/08/21 16:50
35	1012	(ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)	USPAT; US-PGPUB	2004/08/21 17:02
36	8	(nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	USPAT; US-PGPUB	2004/08/21 17:02
37	15	("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))	USPAT; US-PGPUB	2004/08/21 17:02
38	23	((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))) (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))	USPAT; US-PGPUB	2004/08/21 16:51
39	15	@ad<20000412 and (((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))) (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))))	USPAT; US-PGPUB	2004/08/21 17:03
40	6	@rlad<20000412 and (((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))) (("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))))	USPAT; US-PGPUB	2004/08/21 16:51

41	18	<p>@ad<20000412 and (((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))) ("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4)))) @rlad<20000412 and (((nm or nanometer or "nano meter" or angstrom) same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))) ("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter") same ((ic or "integrated circuit") with chip with (cover\$4 or layer\$4 or film or coat\$4) with (protect\$4 or damag\$4))))</p>	USPAT; US-PGPUB	2004/08/21 17:00
42	6237	("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4)	USPAT; US-PGPUB	2004/08/21 17:12
43	28	(nm or nanometer or "nano meter" or angstrom) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))	USPAT; US-PGPUB	2004/08/21 17:02
44	32	((("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter")) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))	USPAT; US-PGPUB	2004/08/21 17:03
45	60	((nm or nanometer or "nano meter" or angstrom) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))) (((("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter")) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4)))	USPAT; US-PGPUB	2004/08/21 17:03
46	38	@ad<20000412 and (((nm or nanometer or "nano meter" or angstrom) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))) (((("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter")) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))))	USPAT; US-PGPUB	2004/08/21 17:12
47	17	@rlad<20000412 and (((nm or nanometer or "nano meter" or angstrom) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))) (((("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter")) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))))	USPAT; US-PGPUB	2004/08/21 17:03

48	45	(@ad<20000412 and (((nm or nanometer or "nano meter" or angstrom) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))) (((("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter")) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4)))))) (@rlad<20000412 and (((nm or nanometer or "nano meter" or angstrom) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))) (((("1" or "1.0" or "2" or "2.0") adj5 ("mu.m" or micron or micrometer or "micro meter")) with (("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4))))))	USPAT; US-PGPUB	2004/08/21 17:03
49	47	("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "entire surface"	USPAT; US-PGPUB	2004/08/21 17:12
50	41	("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "outer surface"	USPAT; US-PGPUB	2004/08/21 17:16
51	88	((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "entire surface") ((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "outer surface"))	USPAT; US-PGPUB	2004/08/21 17:12
52	55	@ad<20000412 and (((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "entire surface") ((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "outer surface"))	USPAT; US-PGPUB	2004/08/21 17:12
53	23	@rlad<20000412 and (((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "entire surface") ((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "outer surface"))	USPAT; US-PGPUB	2004/08/21 17:12
54	58	(@ad<20000412 and (((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "entire surface") ((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "outer surface")))) (@rlad<20000412 and (((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "entire surface") ((("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with "outer surface"))))	USPAT; US-PGPUB	2004/08/21 17:12

55	734	("ic chip" or "integrated circuit chip") with (cover\$4 or layer\$4 or film or coat\$4) with (side or sidewall)	USPAT; US-PGPUB	2004/08/21 17:16
57	18	("4918548" "4972277" "4984106" "5021902" "5059772" "5103986" "5184260" "5237467" "5402283" "5416653" "5442500" "5469310" "5487579" "5498116" "5502697" "5555143" "5659440" "5739978").PN.	USPAT	2004/08/21 17:27
60	8	5128816.URPN.	USPAT	2004/08/21 17:30
61	4	("3658193" "4160281" "4420779" "4807066").PN.	USPAT	2004/08/21 17:31
62	13	3658193.URPN.	USPAT	2004/08/21 17:31
63	0	09/548313	USPAT; US-PGPUB	2004/08/21 18:01
64	9	"6282062"	USPAT; US-PGPUB	2004/08/21 18:08
65	16	("4558510" "4746392" "4760478" "4789914" "4891723" "4991045" "5187625" "5275841" "5282103" "5528819" "5572387" "5594607" "5606477" "5668405" "6014289" "6025648").PN.	USPAT	2004/08/21 18:03
66	8	("4642716" "4739431" "5245489" "5510956" "6084746" "6282062" "6437944" "6498702").PN.	USPAT	2004/08/21 18:04
67	2	("6282062" "6549373").PN.	USPAT	2004/08/21 18:05
68	2	("6282062" "6549373").PN.	USPAT	2004/08/21 18:05
69	15	("5084211" "5245489" "5583720" "5936304" "5995321" "6042894" "6134084" "6166888" "6268980" "6282062" "6339519" "6344248" "6369985" "6437944" "6522502").PN.	USPAT	2004/08/21 18:06
70	14	6134084.URPN.	USPAT	2004/08/21 18:07
71	3	("5305168" "5859746" "6282062").PN.	USPAT	2004/08/21 18:08
72	5	"11250602" "2000195023" "53069623" "55150130" "03108120"	JPO	2004/08/21 18:09